

**IPC-2581B-WAM1**  
**2016 - December**

**Generic Requirements for  
Printed Board Assembly Products  
Manufacturing Description Data  
and Transfer Methodology**

Supersedes IPC-2581B  
September 2013

*An international standard developed by IPC*

*Association Connecting Electronics Industries*



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- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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**IPC-2581B-WAM1**

# **Generic Requirements for Printed Board Assembly Products Manufacturing Description Data and Transfer Methodology**

Developed by Product Data Description (Laminar View) Subcommittee (2-16) of the Electronic Product Data Description Committee (2-10) of IPC

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### **Supersedes:**

IPC-2581B - September 2013  
IPC-2581A - May 2012  
IPC-2581 with Amendment 1 -  
May 2007  
IPC-2581 - March 2004

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## Acknowledgment

Any document involving a complex technology draws material from a vast number of sources across many continents. While the principal members of the Product Data Description (Laminar View) Subcommittee (2-16) of the Electronic Product Data Description Committee (2-10) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

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***A special note of thanks goes to the following individuals for their dedication to bringing this project to fruition. We would like to highlight those individuals who made major contributions to the development of this standard.***

Edward Acheson, Cadence Design Systems Inc.	Ronny Kovartovsky, Frontline PCB Solutions
Kent Balius, TTM Technologies	Humair Mandavia, Zuken USA, Inc.
Tomas Bergsten, Ericsson AB	William Newhard, DownStream Technologies, LLC
Gary Carter	James Pierce, Axiom Electronics, LLC
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